

Full Material Declaration for attached parts list

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Declarations authorised by:

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Declaration effective from: 1 January 2004 [Approved on 23 January 2014, 06:50 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.50000%	Nickel	7440-02-0	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Lead and Lead alloys	0.20000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	Filled thermoplastics	60.00000%	Grilon	25038-54-4	100.00000%
Leadfinish	Tin plating	1.40000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	37.90000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
19X10X3.5	Bridge Rectifier Single Inline	1.3	g